IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Michael S. Leung, et al.

Serial No. : 10/666,399

Filed: September 18, 2003

Examiner : Kalam, Abul

Art Unit : 2814

Customer No. : 23935

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

NOTIFICATION OF FILING OF DIVISIONAL APPLICATION

Notification is hereby being made of the filing of a divisional application for the above application.

Respectfully submitted,

Dated: 9/0/0

Laye G. Heybl Registration No. 42,661 Attorney for Applicants

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(U:JGH/NotofFilDV/P0298US-7)